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DETERIORATION OF FIBERBOARD
BY MOLDS

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DIVISION OF FOREST PATHOLOGY

MADISON 5, WISCONSIN

IN COOPERATION WITH THE

FOREST PRODUCTS LABORATORY

FOREST SERVICE

DETERIORATION OF FIBERBOARD BY MOLDS

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GEORGE H. ENGLERTH, Pathologist1 ear A bha A A Gasers

Division of Forest Pathology² Bureau of Plant Industry, Soils, and Agricultural Engineering Agricultural Research Administration United States Department of Agriculture

The mold resistance of fiberboard has been studied to provide a basis for recommendations on the relative merits of various types of commercial and of experimental fiberboards. The experimental fiberboards were prepared by the Division of Pulp and Paper of the Forest Products Laboratory.

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The scope of these investigations includes:

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- (1) The relative amount of deterioration of various types of commercial fiberboards.
- (2) The resistance to molding of various types of laminating adhesives used in commercial fiberboard samples.
- (3) The protective value of adding a preservative to the adhesive only, to the furnish only, or to both.
- (4) The ability of molds to penetrate the unbroken surfaces of fiberboards.
- (5) The effect of molding and delamination on the tensile and bursting strength of the boards.

The writer wishes to acknowledge the assistance of R. L. Krause, formerly pathologist in the Division of Forest Pathology, who started the study, and T. L. Fletcher, chemist in the Forest Products Laboratory.

In cooperation with the Forest Products Laboratory, maintained by the Forest Service, United States Department of Agriculture, at Madison 5, Wisconsin, in cooperation with the University of Wisconsin,

MATERIALS

Forty samples of commercial fiberboard were tested. These included samples of Vls, V2s, V3s, V3c, W5c, W5s, and W6c, the designations "s" and "c" referring to solid and corrugated types, respectively. "V" fiberboard, grades 1, 2, and 3, was developed primarily for exterior containers for overseas shipment, often requiring high weather resistance. "W" board, grades 5 and 6, also designed to withstand moist conditions, is of lower strength and was developed primarily for use as interior boxes that are overpacked in wood or "V" board for overseas shipment. Table 1 shows the requirements for these different grades as given by joint Army-Navy Specification JAN-P-108 dated June 1944. In most cases the fillers of these boards were laminated with a urea-formaldehyde-starch or a ureaformaldehyde-starch-emulsified asphalt adhesive. The liners were bonded either with these adhesives or with asphalt. Five samples were laminated with a proprietary polyvinyl resin adhesive and one was asphalt impregnated. Two of the boards were laminated with urea-formaldehyde starch containing 0.08 percent sodium pentachlorophenate. Where known, the resin content of the urea-formaldehyde-starch adhesive was about 6 to 8 percent based on the dry weight of the starch.

In addition to the commercial boards, the Division of Pulp and Paper of the Forest Products Laboratory provided experimental solid fiber-boards with and without preservative, and with the furnish composed entirely of reclaimed fiber. Sodium pentachlorophenate was added to the furnish in half of the boards prior to the addition of 3 percent rosin and 3 percent alum as sizing. Two concentrations of the preservative were tried, 1.7 and 2.0 percent. Chemical analysis of the board treated with 1.7 percent sodium pentachlorophenate showed that 0.6 percent of the preservative was retained.

The liners of these boards were laminated with asphalt and the filler with a urea-formaldehyde-starch adhesive containing 20 percent resin based on the weight of the dry starch. Twelve and one-half percent ammonium chloride based on the weight of the resin was added as a catalyzer.

METHODS

All of the test samples were soaked in distilled water at room temperature in order to raise the moisture of the boards to a content favorable for mold development. The soaking period was varied for the different types of fiberboards, depending on preliminary trials and the type of board. The corrugated boards were immersed for 1/4 hour, the solid commercial tensile-tested boards for 1/2 hour, the commercial and experimental Mullen-tested fiberboards for 4 hours, and the experimental tensile-tested boards for 16 hours. The Mullen test is a common bursting test. Half of the samples were inoculated by dipping them in a water suspension of mold spores and bacteria which had previously been isolated

from moldy fiberboard and other cellulose material. No attempt was made to work with pure cultures or specific organisms, but similar inoculum was used throughout the tests. The inoculated samples were incubated for periods up to 12 weeks in a closed container stored in a room maintained at 97 percent relative humidity and 80° F. Water was put in the bottom of the container, but it did not come in direct contact with the specimens. The uninoculated samples or controls were incubated in separate containers under the same conditions except that volatile fungicides were placed in the containers to prevent mold growth. The fungicides used were pyridine, paradichlorobenzene, and Insl-X Volatile Fungicide.

Some of the V-boards were edge-coated with beeswax containing 5 percent pentachlorophenol and 5 percent rosin after the initial soaking and prior to inoculation. The treatment was designed to prevent molding through the edges of the board, and thereby determine the ability of the molds to penetrate the unbroken surface of the board.

Both the wet and dry tensile and bursting strengths of the original boards were determined. At regular intervals, samples of the inoculated and uninoculated boards were removed, data on their condition recorded, and either the bursting strength or the tensile strength determined. One specimen of each treatment was tested as removed from the incubation chamber, and one after being conditioned to equilibrium at 50 percent relative humidity and 80° F. The moisture content of the conditioned boards was between 6 and 8 percent. Boards tested for bursting strength by the Mullen test were punctured in 5 different places and the average for the 5 punctures considered as the bursting strength of the sample. Boards tested for tensile strength were cut into four 1-by 6-inch strips after approximately 1/2 to 1 inch was removed from each side of the board in order to avoid excessive effect from edge molding or delamination. The long dimension of the strips was cut parallel with the machine direction of the board for solid boards or parallel with the corrugations for the corrugated boards.

RESULTS ON COMMERCIAL V-BOARD

All the commercial V-boards molded. The amount of molding, tensile and bursting strength values, and moisture contents are shown in table 2. In general, the deterioration and delamination as a result of action by organisms was not reflected in significant decreases in bursting strength. In some cases the sample was heavily molded and completely delaminated after 12 weeks' exposure, but its bursting strength was still as high or higher than the original strength, or the corresponding uninoculated control. Apparently little actual injury to the fibers took place during the period of the tests. Tensile strength tests reflected loss due to molding and resultant delamination somewhat better than did the Mullen tests.

It was not possible to separate the possible action of bacteria from that of molds in the deterioration and delamination of the fiberboards. As a consequence, when referring to strength loss and delamination by molds in this report the possible effects by bacteria are included with those by molds. It has been shown that a moisture content of at least 55 percent is required for bacteria acting alone to weaken casein-glued plywood joints.

Some of the inconsistencies in results may lie in the lack of uniformity in the fiberboard. Also, differences in moisture content of those specimens tested wet may account for some of the variations in strength values. However, moisture content is not a cause of variation in those samples tested after being conditioned at 50 percent relative humidity and 80° F.

To bring out more clearly the relationship of molding to strength values, table 3 shows the decrease in strength for each test period as compared with the original strength values. For those boards in which tensile tests were made, the decrease in strength is presented in graphic form in figure 1.

The amount of molding on all V-board specimens is summarized in table 2, and the amount of delamination in table 4. Mold development on representative samples after 12 weeks' exposure is shown in figure 2.

Boards laminated with the proprietary polyvinyl resin adhesive were only lightly molded even after 12 weeks' exposure, and showed no delamination. The asphalt-impregnated boards were moderately molded but not delaminated.

All of the solid V-board samples laminated with urea-formaldehyde-starch or with urea-formaldehyde-starch-asphalt emulsion molded readily and began to delaminate after 5 weeks' exposure. Some had completely delaminated after 12 weeks. The addition of 0.08 percent sodium pentachlorophenate in the urea-formaldehyde-starch adhesive did not inhibit mold growth, and the boards so treated molded and delaminated almost as readily as untreated ones.

The corrugated V3 boards molded and delaminated quite readily. The rapid delamination may be explained by the presence of the corrugations, which allowed the inoculation spore suspension to run into the inside of the board.

None of the uninoculated control samples showed any delamination except for the corrugated samples, which were partially delaminated after 12 weeks. The presence of the volatile fungicides in the containers in which these specimens were incubated held molding to a minimum. Since the

³Duncan, Catherine G. The effect of moisture on bacterial delamination of casein-bonded plywood. Office Report, 10 pp. April 1946.

control specimens were incubated under the same conditions with moisture contents approximately the same as the molded specimens, there is little question that the delamination of the solid boards and most of it in the corrugated boards was due to mold attack on the inoculated specimens.

Penetration of Molds

One of the purposes of the study was to determine whether molds are able to penetrate the unbroken surfaces of the fiberboard or whether penetration is dependent upon breaks in the board. In order to obtain information on this question the edges of one set of the boards were sealed with a fungicidal wax before inoculation. In that way the attack by molds was restricted to the surface plies. Detailed notes on the delamination after 7 and 12 weeks' exposure of the inoculated specimens with edges exposed and with the edges sealed are given in table 4. The samples with sealed edges generally were somewhat less delaminated after 7 weeks' exposure than the unsealed samples. After 12 weeks, however, delamination in the sealed specimens was practically as great as in the specimens having their edges exposed. Delamination of the samples with exposed edges generally progressed from the outside toward the center. In many cases these samples had begun to separate along the edges after 5 weeks' exposure.

These observations indicate that the delamination of fiberboard having no other means of entrance for micro-organisms than penetration through the surface plies may be almost as rapid as in fiberboard having open edges. It seems unlikely that organisms may have penetrated the wax seal since no delamination was noted around the waxed edges when the plies were separated for observation.

Small-scale penetration tests with decay fungi on fiberboard with wax-sealed edges showed that two fungi causing brown rots grew through V2s boards in 7 days' time. Certain molds came through V3s board in 15 days.

From these tests it is readily seen that some of the adhesives regularly used in laminating fiberboard are not resistant to attack by micro-organisms when such fiberboard is exposed for extended periods of time to conditions that favor mold growth.

RESULTS ON COMMERCIAL W-BOARD

The results of tensile tests and notes on molding and delamination of W-board are given in table 5. After about 1 week, molding was observed on all of the corrugated boards, and after 3 weeks they were heavily molded. Mold was about, as heavy within the corrugations as on the faces. The solid W5 board laminated with a proprietary polyvinyl resin adhesive

was only lightly molded with no delamination at the end of 12 weeks, while the same type of board laminated with urea-formaldehyde-starch was heavily molded and 90 percent delaminated after 3 weeks.

To illustrate more clearly the decrease in tensile strength of these boards due to molding, the data in table 5 are presented graphically in figure 1.

The tensile strength of all inoculated W-boards was reduced. Since some further loss in the inoculated boards occurred after delamination, it appears that the organisms present decreased the fiber strength. However, a greater part of the decrease in tensile value was apparently due to delamination. No delamination was noted in the uninoculated samples incubated under similar conditions. In evaluating the results, however, differences in moisture content as well as differences in the strength values of individual boards should be recognized.

RESULTS ON EXPERIMENTAL FIBERBOARD

Three sets of experimental fiberboards were prepared and tested against molding. One set had 1.7 percent sodium pentachlorophenate added to the fiber furnish with varying amounts of this preservative added to the urea-formaldehyde-starch adhesive. Chemical analysis showed, however, that only 0.6 percent of the preservative was retained in the fiber. Another set had 2.0 percent sodium pentachlorophenate added to the furnish and varying amounts of the chemical added to the adhesive, while still another was made of untreated furnish:

The results of the Mullen tests made on the boards treated with 1.7 percent sodium pentachlorophenate are recorded in table 6, and those of tensile tests on boards treated with 2.0 percent preservative are recorded in table 7. Notes on molding and delamination and the moisture contents of those specimens that were tested wet are included in the same tables in order to facilitate correlation of the strengths with amount of molding and moisture content.

All the boards without sodium pentachlorophenate added to the furnish molded heavily, and likewise showed a greater reduction in both bursting and tensile strength than did boards with the furnish treated. The loss in tensile strength of the experimental boards tested is illustrated graphically in figure 3. The addition of 2 percent or less of sodium pentachlorophenate in the adhesive gave little or no evidence of preventing deterioration and consequent loss in tensile strength. The incorporation of the preservative in the adhesive as well as in the furnish adds little to the cost and should aid in preventing molding; additional tests with 2 percent and higher concentrations in the adhesive are needed before concluding against it.

The asphalt liners tended to loosen after preliminary soaking and subsequent incubation. The asphalt supported surface mold growth, which indicates that treatment of the asphalt might also be advantageous.

Figure 4 shows the amount of molding of the reclaimed treated and untreated fiberboards after 12 weeks' incubation at 97 percent relative humidity and 80° F.

SUMMARY AND CONCLUSIONS

Mold tests made on various V- and W-fiberboards and experimental fiberboards gave the following results:

- (1) Urea-formaldehyde-starch and urea-formaldehyde-starch-asphalt-emulsion resins in solid V- and W-boards were not mold resistant.
- (2) V- and W-boards laminated with a proprietary polyvinyl resin adhesive were more mold resistant than those boards laminated with other adhesives. Only light molding with no delamination was noted on these boards after 12 weeks.
- (3) Both V and W corrugated boards laminated with ureaformaldehyde-starch molded heavily and were badly delaminated after 3 weeks.
- (4) Uninoculated corrugated and solid boards did not delaminate as readily as inoculated boards.
- (5) Molds penetrated through the surface of the solid fiberboard and caused delamination.
- (6) The addition of 1.7 and 2.0 percent sodium pentachlorophenate to the furnish reduced molding and strength loss appreciably with the higher concentration giving the best results.
- (7) The addition of 2 percent sodium pentachlorophenate to the adhesive gave no evidence of value when the furnish was untreated, or of improving the protection when the furnish was treated. However, until additional evidence is available it would be safest to treat the adhesive, probably using a higher concentration than the 2 percent used in these experiments.
- (8) Asphalt is not mold-inhibiting and should probably be treated along with the other constituents in making a mold-resistant board.

Table 1.--Requirements for V-board and W-board exterior and interior grades

Type:G	rade	: Compliance : symbol	: boa	ugated rd; nom oaliper paperb	inal	: Solid : fiber - : board : nominal : caliper	aver burs	age sting ength	: Maximum :permissible : ply :separation : (wet)
:					:Corru- :gated :mate-2 : rial		Dry:	After 4 hours immer- sion	
:-			<u>In</u> .	In.	In.	In.	Lb.	Lb.	<u>In</u> .
				Ext	erior gr	ades			
SF:	1	:Vls		:	:	0.100	750:	500	1/4
SF:	2	: :V2s		:	A - 0 45	090	550:	500	: 1/4
SF:	3	:V3s		:		090) 400	150	1/4
CF	3	∀3c	0.023	:0.023	.0.010)		
				Int	erior gr	ades			
SF:	5	: :W5s		:	:	.075	:):	7 00	:
CF:	5	: :W5c	.: .016	: .016	: .010	:	:) 275:	100	: 1/4
SF:	6	: :W6s		:		.060			
CF:	6	:w6c	010	.010	: .010	•	:) 175:	50	: 1/4

 $[\]frac{1}{A}$ 5 percent minus and unlimited plus tolerance is permitted.

Corrugations shall be "B" or "C" flute having approximately 50 or 42 flutes per foot, respectively.

Table 2. -- Tensile strength, bursting strength, molding, and moisture content of commercial V-boards subjected to molding at 97 percent relative humidity and 80° F.

10 m 10			Tensile st	rength.			Bursting	strength2/	10.100		: Moist	ure conten	t of wet b	pards
Type of :		Test			i dry	Teste	d wet			Amount	STATE AND STREET, STATE OF	e tests	: Bursting	g tests
board		: Inocu- : lated		Inocu-	Control		: Control	Inocu-	Control	morging	: Inocu- : lated	: Control	Inocu-	Control
7.7	Weeks	Lb. per in.	Lb. per in.	Lb. per	Lb. per in.	Lb. per sq. in.	Lb. per sq. in.	Lb. per sq. in.	Lb. per		Percent	Percent	Percent	Percent
Laminat	ted with ur	ea-formald	ehyde-starch											
Vls	Original 3 6 9	: 214	552 152 340 235 160	292 640 527 588	651 303 609 276 602	815 740	: 840 : 795 : 775 : 750 : 708	843 794 766 731	: 784 : 774		21 25 62 27		23 31 34 34	31 32 40 42 40
V2s			=	:	1.5	651 520	: 601 : 631 : 530 : 556 : 531	558	675 671 640 670 711	: Heavy			: 33	28 26 34 32 32
V3s		: 228	347 291 210 247 223	: 404	482	266 180 162	: 262 : 130 : 160 : 150 : 130	376 314	: 452 : 367 : 299 : 215 : 266		: 33 32 32 : 35	32	38 40 41 41	36 57 47 43 39
V30	6 9	: 34	121 43 43 46 21		: 249	200	: 207 : 180 : 140 : 164 : 187		358 356 334 323 307	: : Medium : Heavy : Heavy : Heavy	56 49 47 46	58 61 48	72 60 52 48	80 66 60 50 39
The state of the s	ted with ur	rea-formald	ehyde-starch	treated w	ith 0.08 pe	ercent sod		hlorophena	THE RESERVE					4
V3s	: 6		=	: =	:	420		526	584 549 558 543 536		=======================================	=	28 34 32 33	32 37 38 37 38
. Laminat	ted with ur	ea-formald	ehyde-starch	-emulsifie	d-asphalt	1						73		
Vls							: 900 : 860 : 906 : 894 : 892		: 764 : 887 : 834 : 803 : 798	: : Heavy : Heavy : Heavy : Heavy			: : 36 : 32 : 33 : 34	33 36 36 32 31
¥2s		ΙΞ			:	618 611 604	: 604 : 666 : 600 : 597 : 623		: 601 : 581 : 568 : 557 : 550	: Light : Medium : Heavy : Heavy			: : 22 : 26 : 27 : 30	27 21 24 26 27
V3a	Original	: 360 : 303 : 280	: 370	: 637 : 540	: 811 : 642 : 754 : 715	404 389 418	: 426 : 364 : 288 : 303	#60 #20	428 454 458 444	Light Medium	29 32 35 35	26	: : 29 : 34	12 35 37 38 38
Agnheli	t impregnat		339	: 500	726	: 486	: 326	: #00	• +2+	. neavy	. 50		•	.)
	: Original	:		=	: =		: 488 : 326	504	: 530 : 506	: : Light	: =		:	: 23 : 36
	6 9			=	:::::::::::::::::::::::::::::::::::::::	408 421		: 530	: 530 : 478	: Medium : Medium : Medium	=		: 28	23 36 34 34 33
. Laminat	ted with a	proprietar	y polyvinyl	resin adhe	sive								1 1 1 1 1 1 1 1	* 10
₹28	Original 3 6 9 12	: : 315 : 254 : 116 : 270	: 415 : 265 : 175 : 196 : 179	462 532 194 560	: 513	565	: 602 : 686 : 518 : 478 : 479	: 606	: 628 : 594 : 614 : 608 : 618		25 28 28 29 28	: 33	18 27 24 25	23 27 28 24 33
V38	Original	<u>=</u>	=		=	299 276 268 265	237 234 238 258 258 276	476	518 507 492 475 444	: Light : Light : Light : Light : Light	= =		 44 57 46 45	58 69 68 71 49

 $[\]frac{1}{4}$ An average of 4 tests for each board.

^{2/}An average of 5 punctures for each of 1 or 2 boards.

^{3/}The uninoculated control samples were incubated under similar conditions as the inoculated ones except for the addition of volatile fungicides. The original strength figures apply to both.
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Table 3. --Degrease in tensile and bursting strength of V-boards subjected to molding at 97 percent relative humidity and 80° F. Based upon strength loss in comparison to original boards.

To e of	** **	186	Tes	Tested wet	Wet		Tested dry	dry	••	ghi ¹	Tested wet	1 wet		=	Tested dry	dry	••	Tensile tests	e tes	ste	: Bursting		tests
board	• •• •• ••	period	Inocu-		Control	H	Inocu-	Control	.01	Ino	Inocu- lated	Control	rol	Inocu-	i pe	Control	÷	Inocu-	Con	Control	Inocu-		Control
	×	Weeks	Percent		Percent	Ā	Percent	Percent	lit.		Percent	Percent	1	Percent	ent	Percent		Percent	Per	Percent	Percent		Percent
Laminated		with t	rea-for	malc.	urea-formaldehyde-starch	sarc	аı																
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Laminated	-	with 1	rea-for	malc	lehyde-st	tarc	h treated	ed with	0.0	2	ercent	sodium	7	pentachlor		ophenate							
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Laminated Vls :		129 62 129 129 129 129 129 129 129 129 129 12	urea-for		-formaldehyde-starch		1		ed-asphal	4	15 : 15 : 29 : 32	9	ੜੇਜ਼ਜ਼ਜ		ご注い	\$2.t.\$	1	1111		1111	**************************************		2222
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V38		W0 0 01	2552		23 22		2322	12 ::	1200		rvo.α⊐‡		23822		F-0-1-0	444	,	Sare Sare		8785 8785	244°		WWWW WF-80.80
Asphalt		1mpregn	nated																				
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Kribkum ovici 800 pue relative percent 16 at molding a 10 exposure weeks! and 12 1 after samples fiberboard commercial of delamination offer on another - Indiah ko af Table

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A. Laminated with urea-formaldehyde-starch Vis : Delaminated to depth of 1/2 to 1-1/2 inches from edges: V2s : Delaminated except for small :	Edges sealed		
Laminated with urea-formaldehyde-starch Vis : Delaminated to depth of : 1/2 to 1-1/2 inches from edges : V28 : Delaminated except for small		ಗಾತ್ರಗಳ ಇತ್ಯಾಣಗಳ	Edges sealed
: Delaminated to depth of : 1/2 to 1-1/2 inches from edges : : Delaminated except for small :			
: Delaminated except for small :	10% delamination	: All plies delaminated except for small area at center of each ply	: 90% delamination
•	90% delamination	: Completely delaminated	: Completely delaminated
V3s : 85% delamination : 5	50% delamination	: Completely delaminated	: Completely delaminated
V3c : Completely delaminated : 1	45% delamination	: Completely delaminated	: 80% delamination
B. Laminated with urea-formaldehyde-starch tres	treated with 0.08% sodium	pentachlorop	
V3s : Outer plies 50% delaminated : : Inner plies delaminated along : edges :	60% delamination	: Outer plies completely delaminated : Inner plies 70% delaminated :	: 80% delamination
C. Laminated with urea-formaldehyde-starch-emulsifled-asphalt adhesive	ulsified-asphalt adhea	sive	
Vis : 60% delamination of outer plies : 3	30% delamination of outer plies only	: Outer plies completely delaminated : No delamination of inner plies	: 50% delamination of outer plies
V2s : Delaminated except for small : A area at center :	No delamination	: Completely delaminated	: Completely delaminated
V3s : 90% delamination : 1	15% delamination	: Outer plies completely delaminated : Inner plies delaminated around edges	: Outer plies completely delaminated : Inner plies 50% delaminated
D. Asphalt impregnated			
V2s : No delamination : N	No delamination	: No delamination	: No delamination
E. Laminated with a proprietary polyvinyl resir	resin adhesive		10 13 13 13 13 13 13 13 13 13 13 13 13 13
V2s : No delamination : N	No delamination	: No delamination	: No delamination
V3s : No delamination : N	No delamination	: No delamination	: No delamination
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Table 3. - Tendile attending melding deligningtion, and maintended eller- a melder

Table 5.--Tensile strength, molding, delamination, and moisture content of commercial W-boards subjected to molding at 97 percent relative humidity and 80° F.

Type of boar	:	Test period	:-	Test	ed.	wet	:	Test	ed.	dry	-:	conwet	te	ture ent of oards	:	of mold-	: :			
1	:		:	Inocu- late	-: d:	Con-,	2:	Inocu-	-:(l:	Contro	1:	Inocu-	-: d:	Control	:		: In	ocu- ated	: C	ontrol
		Weeks											-	Percent						ercent
	:	***************************************	:							in.		cent			:		-	ent	-	
	:		:		:	4, 29, 100			:		:		:		:		: -		:	
Α	Lai	ninated	W	ith u	rea	a-ior	na	Idenyo	le-	-starc	h	1								
W5c	: (Origina.	1:		:	54	•		:	184	:	***	:	31	:		:		:	
	:	3	:	28	:	36	:	127	:	170	:	55	:	60	: F	Heavy	:	90	:	0
	2	6	:	22	•	40	:	103	*	180	:	49	:	55	: F	leavy	:	95	:	5
	•	9	:	23	:	39	:	96	:	176		43	:	56		leavy		.00	:	10
	:	12	:	21	:	32	:	83	:	168	:	45	:	79	: 7	Tery	; 1	.00	:	25
	:		:		:		:		:		:					heavy	:		:	
			:		:		:		:		:		:		:		:		:	
W5s	: (Origina.	l:		:	207	:		:	452	:			29		m10-0	:		:	
	:	3	:	37		41	:	210	:	373	:	59	:	68	:1	leavy .	:	90	:	0
	:	6	:	29	:	89	:	177	:	339	:	48	:	46	2 %	/ery	:	90	:	0
			:		:		:		:		:		:			heavy			:	
	:	9	:	33	:	96	:	137		393	:	39	:	41		ery		.00	:	10
	*				:		:	27,			:					heavy			:	
		12	:	17	:	113	:	139	:	400	:	39	:	49		ery		.00	:	10
			:		:		:				:		:			heavy			:	
	1		:		:						:									
W6c	. (Origina	1:		:	40	:			135			:	33						
No. of Contract		3	:	23		29	:	93		126		52			• F	leavy		75		0
	:	6	•	17	•	31	•	73	•	141		48				leavy		95		5
	•	9	•	15		33	•	58	•	130		41	•	49		Jery .				10
	•					,00				444		**				heavy				
	•	12		13		16		42		127		37		92		Tery		.00	1	20
	:	-	:		:		•		:		:		:	22		heavy			:	~~
B. 1	Lai	minated	w	ith a	מ	roprie	et	ary po	oly	vinyl	r	esin a	ad	hesive						
											7						1			
WOS		Origina.		200		291	:			348	:		•	16	:		:		:	
5.	:	3		208		191		331	:	344	:		:			Light		0	:	0
	:	6		192		135	:	326	•	345	:	24		32		light		0	:	0
	:	9		193		158	*	305	\$	314	:	25	:	27		Light		0	:	0
	:	12	:	186	:	196	:	354	:	351				30	:]	Light	:	0	:	0
	:		:		:		:		:		:		:		:		:		1	

Average of 4 tests for each board.

²The uninoculated control samples were incubated under similar conditions as the inoculated ones except for the addition of volatile fungicides. The original strength figures apply to both.

Table 6. -- Bursting strength, molding, delamination, and moisture content of experimental fiberboards treated with varying amounts of sodium pentachlorophenate and subjected to molding at 97 percent relative humidity and 80° F.

			••	•••		4	pareting	1	Pringing of							Molature content	00	ntent
Sample	: Preservative	tve	Test	i	Tested wet	ed			Tested dry	d d	ry		Amount	Amount		of wet specimens	spec	lmens
			por led		Inocu- lated		Control2/		Inocu-	Ö	Control		molding	ination	u	Inocu-		Control
	Percent	41	Weeks	 H @	Lb. per		Lb. per		Lb. per sq. in.	امالتا	Lb. per sq. in.					Percent		Percent
98	Furnish Adhesive	00	original 3 7		2000 30149 30149		1111		500 5111 4112 732		1111	444	Light Very heavy	Slight Heavy		23 7 7 2 8 4 4 7 8		1111
80	Furnish Adhesive	0.0	: Original		577		1500 1500 1500 1500 1500		4757 4600 1000		530	山田田	Light Heavy	o 0 Slight		1822		2000
100	Furnish Adhesive	000	: Original 3 7 12	/	600 328 141		57550 57550 17850 17850		511 402 		1480 1461 532	「山田Þ	Light Heavy Very heavy	Slight Heavy		1222		\$ 2000 \$ 2000
8	Furnish Adhesive	000	: Original		563 379 393		516		546 432 392		75716 747578 7470578	山田田	Light Heavy Heavy	Medium		73.00 1		119 26 25 25
# WO	Furnish Adhesive	7.0	original:		526 412 371		4444 4827 4827		144 0000 1000 1000		535	ZLZ	None Light Redlum :	 0 0 811ght		1226		223
90	Furnish Adhesive	0.5	: Original 3 7 : 12		515 513 513		4 4 4 6 2 2 3 3 4 4 4 5 3 5 3 5 4 7 4 7 7 7 7 7 7 7 7 7 7 7 7 7 7 7 7	<u>.</u>	5553		47 47 47 47 47 47 47 47 47 47 47 47 47 4	L C C	Very 11ght: Very 11ght: Light:	1000	•••••	14%0		2020
80 77	Furnish Adhesive	1.0	: Original 3 7 12 12		13212		4500 th 4500 t		4725 4725 5625		1462 502 516	ZUZ	None :: Light ::	1000		1 555		5883
91	Furnish Adhesive	2.0	original		19261		4474 4960 93780		527		44533 4661 4661	L dz	None Very 11ght :	1000		229		5500d

1/Each figure is an average of 5 punctures.

2/The uninoculated control samples were incubated under similar conditions as the inoculated ones except for the addition of volatile fungicides. The original strength figures apply to both.

Table 7 .-- Tensile strength, molding, delamination, and moisture content of experimental fiberboards treated with varying amounts of sodium pentachlorophenate and subjected to molding at 97 percent relative humidity and 80° F.

	••			••		H	Tensile strength!	rei	ngth-1/					Amount	Mot	Moisture content	cont	ent
Sample	: Preservative	94	Test	i	Tested wet	ed	wet		Tested dry	d dr	y	· P	Amount of :	of	Jo	of wet specimens	pecim	ens
nber	sdded:		period		Inocu-		Control		Inocu-	8	Control		gritato.	nation	Inocu-	cu- ted	Con	Control
			Weeks	ļ	Lb. per	İ	Lb. per	ļ	Lb. per	의	Lb. per				Per	Percent	Per	Percent
66	Furnish Adhesive	00	Original		1112 85 85		1388 1788 1788 1788 1788 1788 1788 1788		1959 1617 1617 1617		229 207 207 229	> H H H	Very light : Heavy : Heavy :	Light Heavy		13885		8283
101	Furnish Adhesive	00	original		14222		1281 1481		122		237 176 176 176	1888	Light Heavy Heavy	Light Light Medium		1 2 8 8 8 9	20 00 20 00 00	8122
103	Furnish	0.0	original 5		1335		122		1832		242 224 217 217 217	HHHE	Light Heavy Heavy	O 0 811ght Heavy		17488		88856
105	Furnish Adhesive	00	original		141 152 750 70 70		1112 122 123 123 123 123 123		126		208 208 1993 1993	Jee .	Light Heavy Heavy	Slight 3/ Slight Medium		12284		ないないない
8 0	Furnish Adhesive	00	original		17402		1122		224 215 215 185		222 222 222 222 222 222		race frace frace fery light	Slight		1278		28485
100	Furnish Adhesive	90	original		17535		11111	**********	1833		452	*****	None None Very light	0 0 0 811ght		25,5%		11111
102	Furnish Adbesive	1.0	original		15221		173		2002 1		241 232 220 227	F444	Very light Very light Very light Light	Slight 3/		174277		12221
5	Furnish Adhesive	00	Original 5 6 12 12		14253		1257		242 280 207 207		239 227 224 213		Very light Very light Very light Very light	 0 0 811ght 14/		12000		22888

Lach figure is an average of 4 tests.

2/The uninoculated control samples were incubated under similar conditions as the inoculated ones except for the addition of volatile fungicides. The original strength figures apply to both.

Jouter plies only.

Z M 69335 F

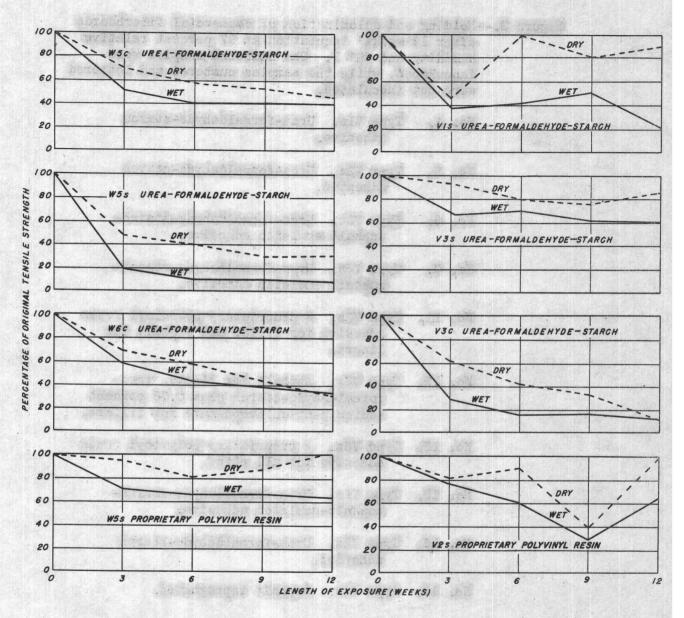
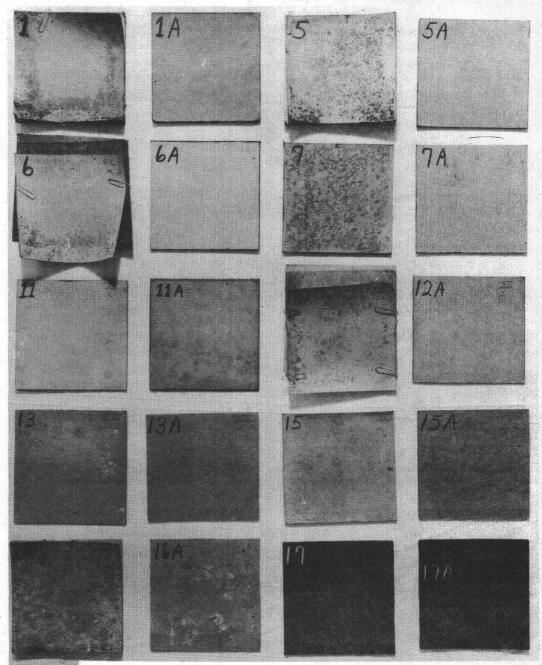


FIGURE 1.--WET AND DRY TENSILE STRENGTH OF V-ANDW-BOARDS EXPOSED TO MOLDING AT 97 PERCENT RELATIVE HUMIDITY AND 80° F.

Z M 67475 1

- Figure 2.—Molding and delamination of commercial fiberboards after 12 weeks' incubation at 97 percent relative humidity and 80° F. The numbered samples were inoculated, while the samples numbered and lettered were not inoculated.
 - No. 1. Type Vls. Urea-formaldehyde-starch adhesive.
 - No. 5. Type V2s. Urea-formaldehyde-starch adhesive.
 - No. 6. Type V2s. Urea-formaldehyde-starch-asphalt emulsion adhesive.
 - No. 7. Type V3s. Urea-formaldehyde-starch-asphalt emulsion adhesive.
 - No. 11. Type V2s. A proprietary polyvinyl resin adhesive for filler and asphalt for liners.
 - No. 12. Type V3s. Asphalt for liners, ureaformaldehyde-starch plus 0.08 percent sodium pentachlorophenate for fillers.
 - No. 13. Type V3s. A proprietary polyvinyl resin adhesive for all plies.
 - No. 15. Type Vls. Urea-formaldehyde-starch-asphalt-emulsion adhesive.
 - No. 16. Type V3s. Urea-formaldehyde-starch adhesive.
 - No. 17. Type V2s. Asphalt impregnated.



Z M 70356 F

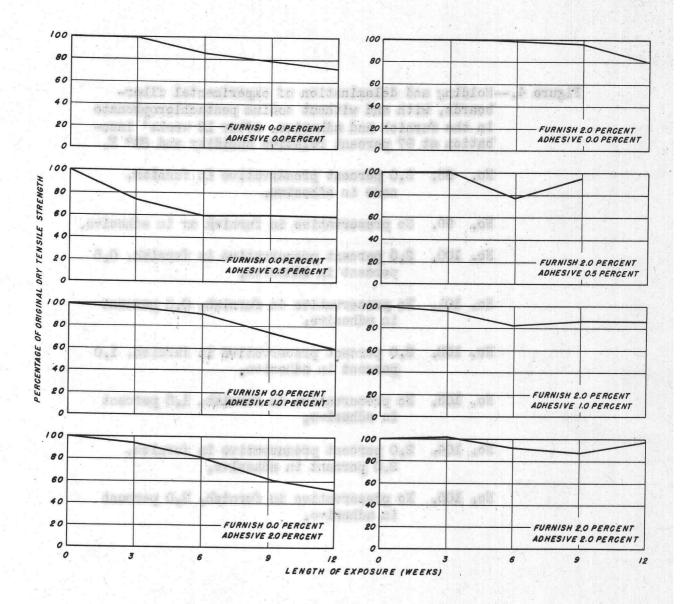
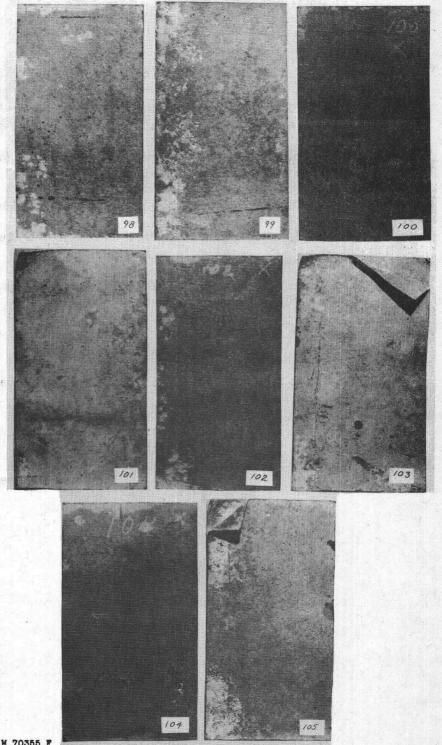


Figure 3.--Tensile strength of reclaimed fiberboard treated with sodium pentachlorophenate and subjected to molding at 97 percent relative humidity and 80° F.

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- Figure 4.—Molding and delamination of experimental fiberboards, with and without sodium pentachlorophenate in the furnish and adhesive, after 12 weeks' incubation at 97 percent relative humidity and 80° F.
 - No. 98. 2.0 percent preservative in furnish, none in adhesive.
 - No. 99. No preservative in furnish or in adhesive.
 - No. 100. 2.0 percent preservative in furnish, 0.5 percent in adhesive.
 - No. 101. No preservative in furnish, 0.5 percent in adhesive.
 - No. 102. 2.0 percent preservative in furnish, 1.0 percent in adhesive.
 - No. 103. No preservative in furnish, 1.0 percent in adhesive.
 - No. 104. 2.0 percent preservative in furnish, 2.0 percent in adhesive.
 - No. 105. No preservative in furnish, 2.0 percent in adhesive.



Z M 70355 F